

#### 20V P-CHANNEL ENHANCEMENT MODE MOSFET

#### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub> @ T <sub>A</sub> = 25°C
	495mΩ @ V <sub>GS</sub> = -4.5V	-0.77A
-20V	690mΩ @ V <sub>GS</sub> = -2.5V	-0.67A
	960mΩ @ V <sub>GS</sub> = -1.8V	-0.57A

This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(on)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Portable electronics

#### **Features and Benefits**

- Footprint of just 0.6mm<sup>2</sup> thirteen times smaller than SOT23
- 0.4mm profile ideal for low profile applications
- Low Gate Threshold Voltage
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- ESD Protected Gate 3KV
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.001 grams (approximate)

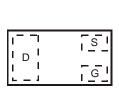




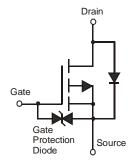
**Description and Applications** 



**Bottom View** 



Top View Internal Schematic



Equivalent Circuit

#### Ordering Information (Note 3)

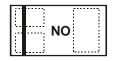
Ī	Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
	DMP21D0UFB4-7B	NO	7	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 3. For packaging details, go to our website at http://www.diodes.com.

### **Marking Information**

DMP21D0UFB4-7B



Top View Bar Denotes Gate and Source Side

NO = Product Type Marking Code



#### Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	-20	V
Gate-Source Voltage			V <sub>GSS</sub>	±8	V
Continuous Drain Current	Steady State	$T_A = 25$ °C (Note 4) $T_A = 85$ °C (Note 4) $T_A = 25$ °C (Note 5)	I <sub>D</sub>	-0.77 -0.55 -1.17	А
Pulsed Drain Current (Note 6)			I <sub>DM</sub>	-5.0	A

## Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P <sub>D</sub>	0.43	W
Power Dissipation (Note 5)	P <sub>D</sub>	0.99	W
Thermal Resistance, Junction to Ambient (Note 4)	R <sub>0JA</sub>	293	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	126	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

#### **Thermal Characteristics**

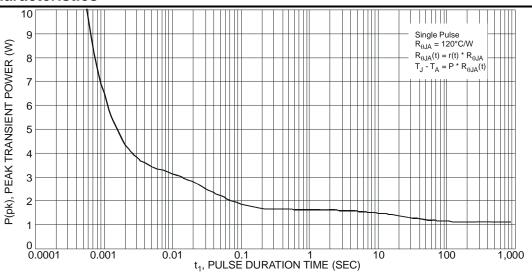
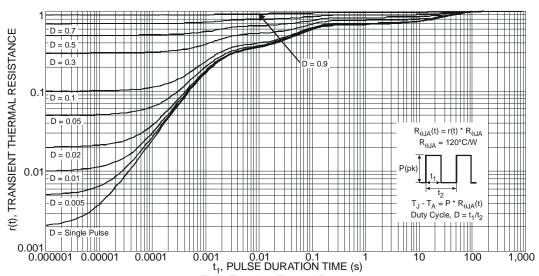


Fig. 1 Single Pulse Maximum Power Dissipation





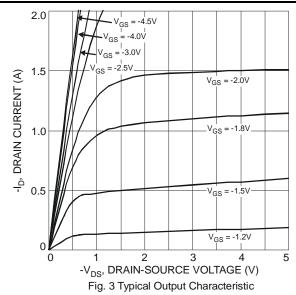
#### Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

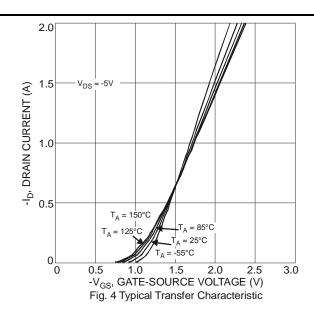
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	-	-	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = 25°C	I <sub>DSS</sub>	-	-	-1	μΑ	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	1	-	±10	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)						_	
Gate Threshold Voltage	$V_{GS(th)}$	1	-0.7	-	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
				495		$V_{GS} = -4.5V, I_D = -400mA$	
Static Drain-Source On-Resistance	R <sub>DS</sub> (ON)	-	-	690	mΩ	$V_{GS} = -2.5V, I_D = -300mA$	
				960		$V_{GS} = -1.8V, I_D = -100mA$	
Forward Transfer Admittance	Y <sub>fs</sub>	50	-	-	mS	$V_{DS} = -3V, I_{D} = -300 \text{mA}$	
Diode Forward Voltage	$V_{SD}$	1	-	-1.2	V	$V_{GS} = 0V, I_{S} = -300mA$	
DYNAMIC CHARACTERISTICS							
Input Capacitance	C <sub>iss</sub>	-	76.5	-	pF	101/11/101/	
Output Capacitance	Coss	-	13.7	-	pF	$V_{DS} = -10V, V_{GS} = 0V,$ - f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	-	10.7	-	pF	T = 1.0MHZ	
Gate Resistance	Rg	-	195	-	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge	Qg		1.5	-	nC	$V_{GS} = -8V, V_{DS} = -15V, I_{D} = -1A$	
Total Gate Charge	$Q_g$	-	1.0	-	nC	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	
Gate-Source Charge	Q <sub>gs</sub>	-	0.2	-	nC	$V_{GS} = -4.5V, V_{DS} = -15V,$ $I_{D} = -1A$	
Gate-Drain Charge	$Q_{gd}$	-	0.3	-	nC		
Turn-On Delay Time	t <sub>D(on)</sub>	-	7.1	-	ns	$V_{DS} = -10V, -I_{D} = 1A$ $V_{GS} = -4.5V, R_{G} = 6\Omega$	
Turn-On Rise Time	t <sub>r</sub>	-	8.0	-	ns		
Turn-Off Delay Time	t <sub>D(off)</sub>	-	31.7	-	ns		
Turn-Off Fall Time	t <sub>f</sub>	-	18.5	-	ns		

Notes:

- 4. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout
- Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate
   Device mounted on minimum recommended pad layout test board, 10μs pulse duty cycle = 1%.
   Short duration pulse test used to minimize self-heating effect.

## **Typical Characteristics**







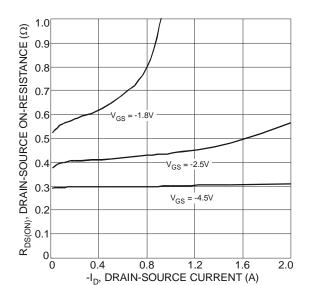
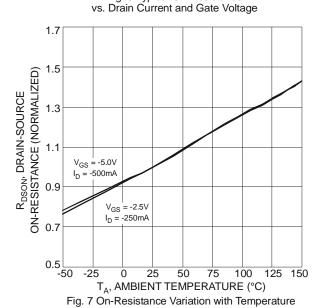


Fig. 5 Typical On-Resistance



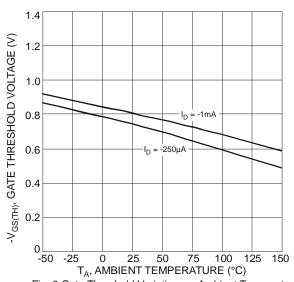
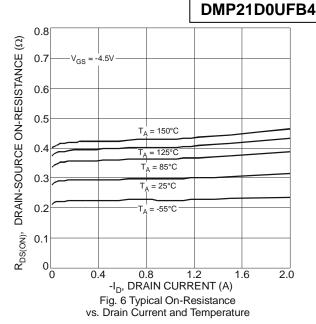
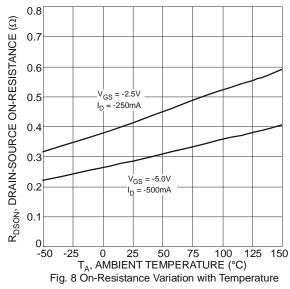
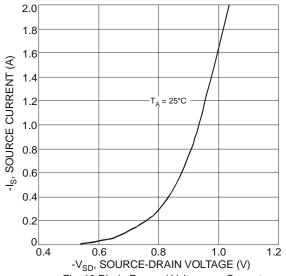


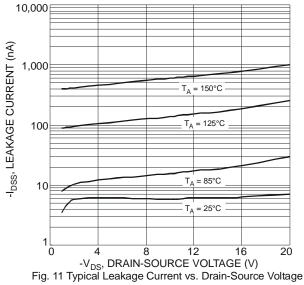
Fig. 9 Gate Threshold Variation vs. Ambient Temperature

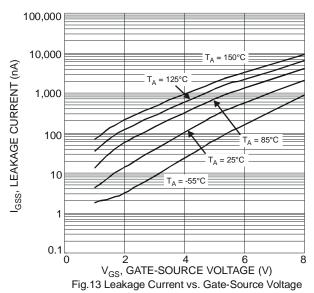


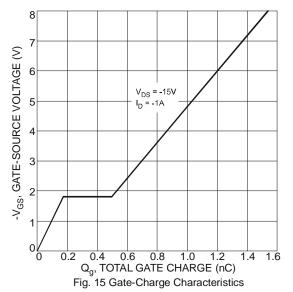


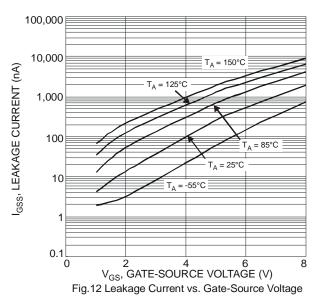


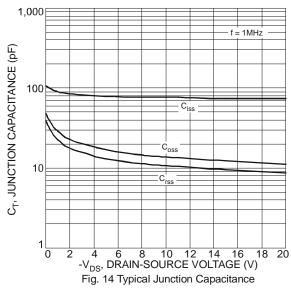






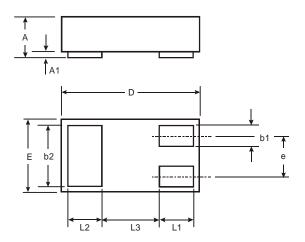






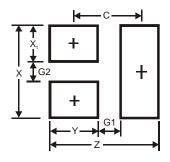


## **Package Outline Dimensions**



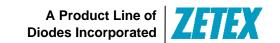
X2-DFN1006-3				
Dim	Min	Max	Тур	
Α		0.40	_	
A1	0	0.05	0.03	
b1	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
D	0.95	1.05	1.00	
Е	0.55	0.65	0.60	
е	_	_	0.35	
L1	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3			0.40	
All Dimensions in mm				

## **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
Х	0.7
X1	0.25
Υ	0.4
C	0.7





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